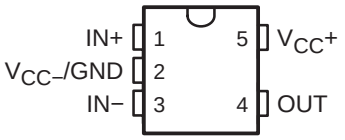
- **Wide Range of Supply Voltages, Single Supply 3 V to 30 V, or Dual Supplies**
- **Class AB Output Stage**
- **True Differential-Input Stage**
- **Low Input Bias Current**
- **Internal Frequency Compensation**
- **Short-Circuit Protection**

DBV PACKAGE
(TOP VIEW)



description/ordering information

The TL343 is a single operational amplifier similar in performance to the μA741, but with several distinct advantages. It is designed to operate from a single supply over a range of voltages from 3 V to 30 V. Operation from split supplies also is possible, provided the difference between the two supplies is 3 V to 30 V. The common-mode input range includes the negative supply. Output range is from the negative supply to V_{CC} − 1.5 V.

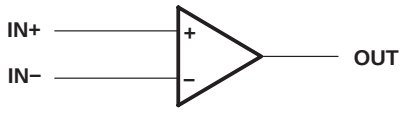
ORDERING INFORMATION

T_A	V_{IO}MAX AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
−40°C to 125°C	10 mV	SOT-23-5 (DBV)	Reel of 3000	TL343IDBVR	T4I_
			Reel of 250	TL343IDBVT	

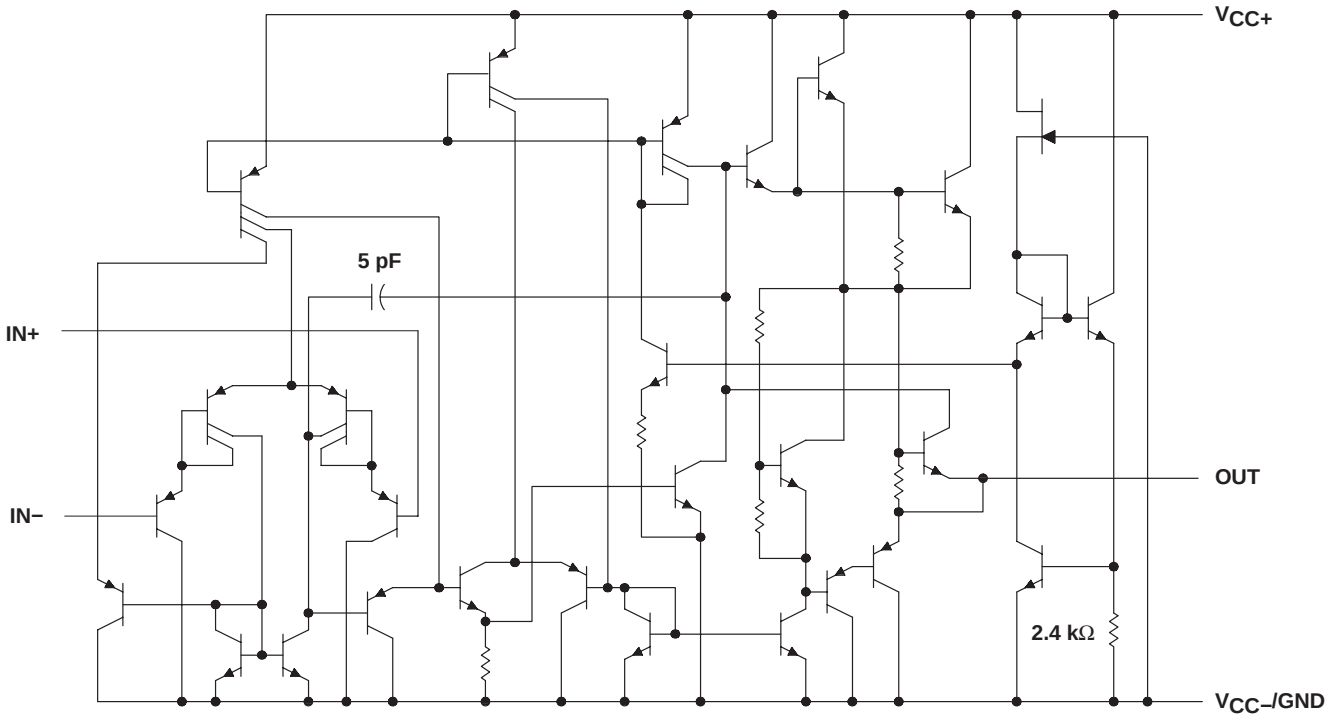
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ The actual top-side marking has one additional character that designates the assembly/test site.

symbol



schematic



NOTE A: Component values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		MAX	UNIT
Supply voltage (see Note 1)	V_{CC+}	18	V
	V_{CC-}	−18	
Supply voltage, V_{CC+} with respect to V_{CC-}		36	V
Differential input voltage (see Note 2)		±36	V
Input voltage (see Notes 1 and 3)		±18	V
Package thermal impedance, θ_{JA} (see Notes 4 and 5)		206	°C/W
Operating virtual junction temperature, T_J		150	°C
Storage temperature range, T_{stg}		−65 to 150	°C

NOTES: 1. These voltage values are with respect to the midpoint between V_{CC+} and V_{CC-}.
2. Differential voltages are at IN+ with respect to IN−.
3. Neither input must ever be more positive than V_{CC+} or more negative than V_{CC-}.
4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Selecting the maximum of 150°C can affect reliability.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V_{CC}	Single-supply voltage	3	30	V
V_{CC+}	Dual-supply voltage	1.5	15	V
V_{CC-}		−1.5	−15	
T_A	Operating free-air temperature	−40	125	°C

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	See Note 6		25°C		2	10	mV
				Full range			12	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	See Note 6		Full range		10		µV/°C
I_{IO}	Input offset current	See Note 6		25°C		30	50	nA
				Full range			200	
$\alpha_{I_{IO}}$	Temperature coefficient of input offset current	See Note 6		Full range		50		pA/°C
I_{IB}	Input bias current	See Note 6		25°C		−200	−500	nA
				Full range			−800	
V_{ICR}	Common-mode input voltage range‡			25°C	V_{CC-} to 13	V_{CC-} to 13.5		V
V_{OM}	Peak output-voltage swing	R_L = 10 kΩ		25°C	±12	±13.5		V
		R_L = 2 kΩ		25°C	±10	±13		
				Full range	±10			
A_{VD}	Large-signal differential voltage amplification	V_O = ±10 V,	R_L = 2 kΩ	25°C	20	200		V/mV
				Full range	15			
B_{OM}	Maximum-output-swing bandwidth	V_{OPP} = 20 V, THD ≤ 5%,	A_{VD} = 1, R_L = 2 kΩ	25°C		9		kHz
B_1	Unity-gain bandwidth	V_O = 50 mV,	R_L = 10 kΩ	25°C		1		MHz
ϕ_m	Phase margin	C_L = 200 pF,	R_L = 2 kΩ	25°C		44		Deg
r_i	Input resistance	f = 20 Hz		25°C	0.3	1		MΩ
r_o	Output resistance	f = 20 Hz		25°C		75		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}(min)		25°C	70	90		dB
k_{SVS}	Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC\pm}$ = ±2.5 to ±15 V		25°C		30	150	µV/V
I_{OS}	Short-circuit output current§			25°C	±10	±30	±55	mA
I_{CC}	Total supply current	No load,	See Note 6	25°C		0.7	2.8	mA

† All characteristics are measured under open-loop conditions, with zero common-mode voltage, unless otherwise specified. Full range for T_A is −40°C to 125°C.

‡ The V_{ICR} limits are linked directly, volt-for-volt, to supply voltage; the positive limit is 2 V less than V_{CC+}.

§ Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.

NOTE 6: V_{IO}, I_{IO}, I_{IB}, and I_{CC} are defined at V_O = 0.

electrical characteristics, V_{CC+} = 3 V and 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	V_O = 1.5 V and 2.5 V			2	10	mV
I_{IO}	Input offset current	V_O = 1.5 V and 2.5 V			30	50	nA
I_{IB}	Input bias current	V_O = 1.5 V and 2.5 V			−200	−500	nA
V_{OM}	Peak output voltage swing‡	R_L = 10 kΩ		3.3	3.5		V
A_{VD}	Large-signal differential voltage amplification	V_O = 1.7 V to 3.3 V,	R_L = 2 kΩ	20	200		V/mV
k_{SVS}	Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC\pm}$)	$V_{CC\pm}$ = ±2.5 V to ±15 V				150	µV/V
I_{CC}	Supply current	V_O = 1.5 V and 2.5 V,	No load		0.7	1.75	mA

† All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.
‡ Output swings essentially to ground.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C, A_{VD} = 1 (unless otherwise noted)

PARAMETER		TEST CONDITIONS				TYP	UNIT
SR	Slew rate at unity gain	V_I = ±10 V,	C_L = 100 pF,	R_L = 2 kΩ,	See Figure 1	1	V/µs
t_r	Rise time	ΔV_O = 50 mV,	C_L = 100 pF,	R_L = 10 kΩ,	See Figure 1	0.35	µs
t_f	Fall time	ΔV_O = 50 mV,	C_L = 100 pF,	R_L = 10 kΩ,	See Figure 1	0.35	µs
	Overshoot factor	ΔV_O = 50 mV,	C_L = 100 pF,	R_L = 10 kΩ,	See Figure 1	20%	
	Crossover distortion	$V_{I(PP)}$ = 30 mV,	V_{OPP} = 2 V,	f = 10 kHz		1%	

PARAMETER MEASUREMENT INFORMATION

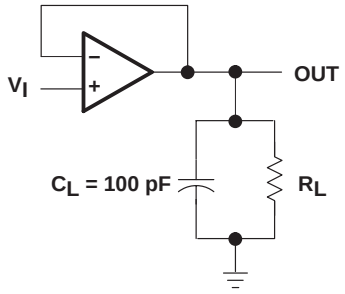


Figure 1. Unity-Gain Amplifier

TYPICAL CHARACTERISTICS†

INPUT BIAS CURRENT vs FREE-AIR TEMPERATURE

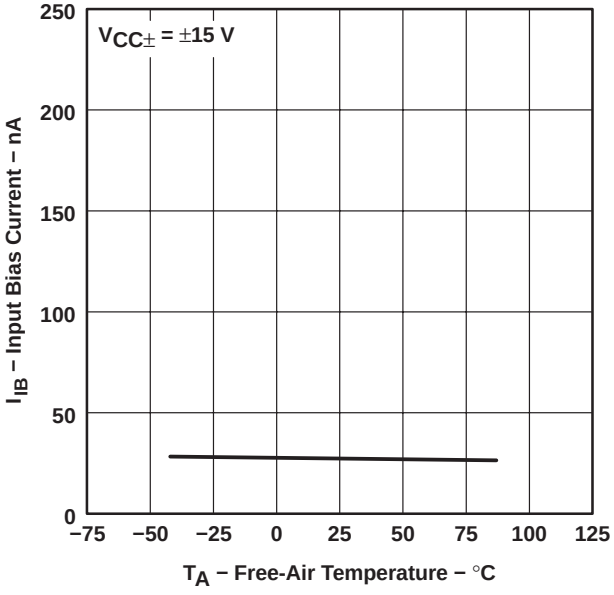


Figure 2

INPUT BIAS CURRENT vs SUPPLY VOLTAGE

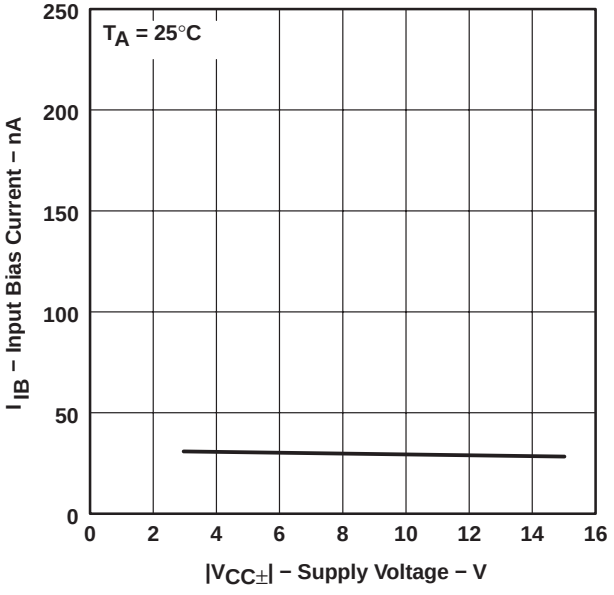


Figure 3

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs SUPPLY VOLTAGE

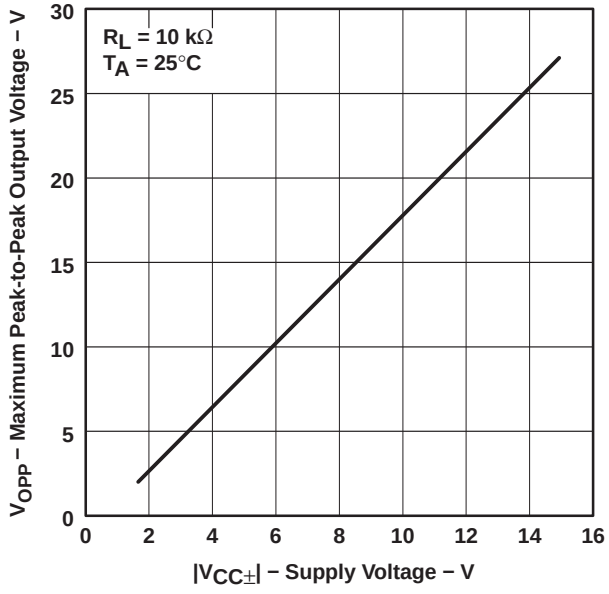


Figure 4

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs FREQUENCY

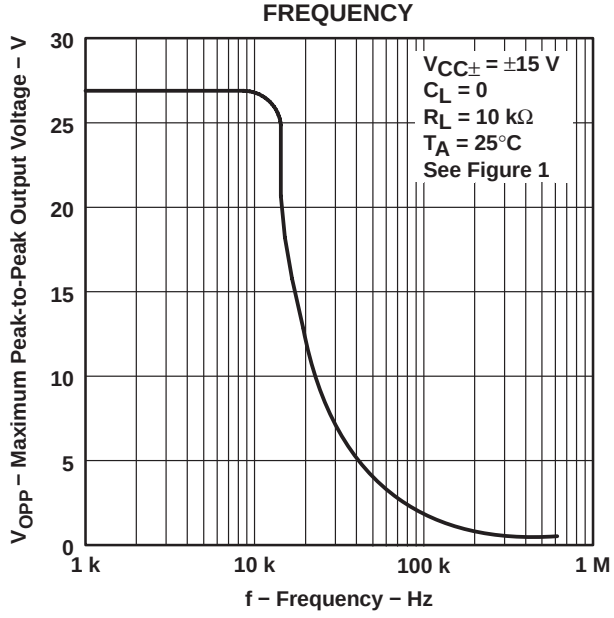


Figure 5

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

TYPICAL CHARACTERISTICS†

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREQUENCY

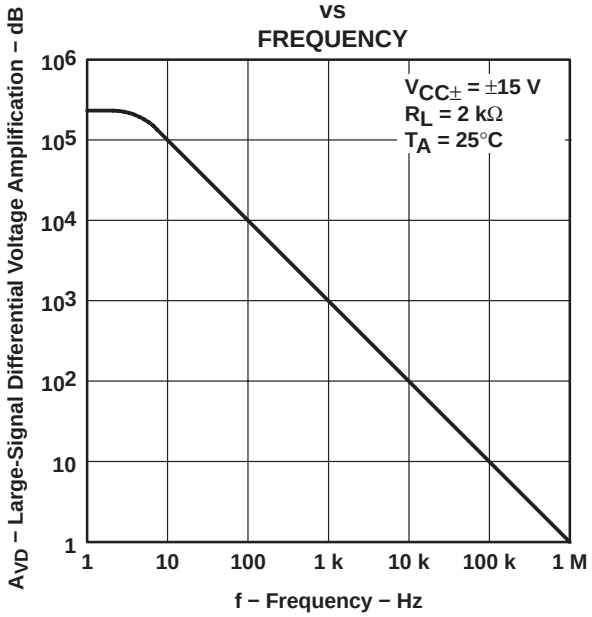


Figure 6

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE

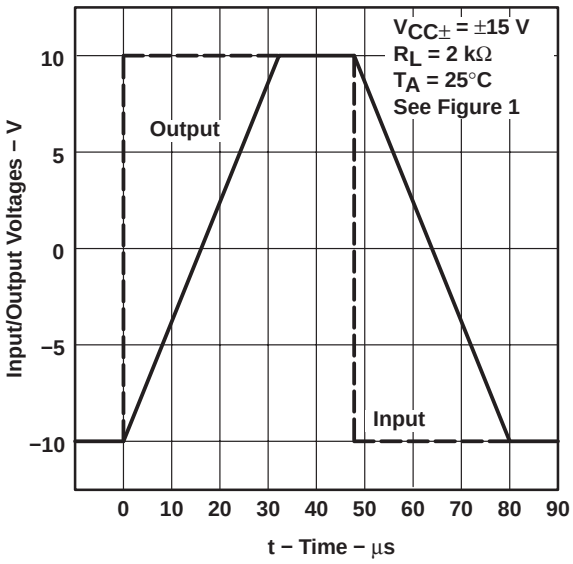


Figure 7

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL343IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(T4I3 ~ T4IG ~ T4IL ~ T4IS)	Samples
TL343IDBVRE4	ACTIVE	SOT-23	DBV	5		TBD	Call TI	Call TI	-40 to 85		Samples
TL343IDBVRG4	ACTIVE	SOT-23	DBV	5		TBD	Call TI	Call TI	-40 to 85		Samples
TL343IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(T4I3 ~ T4IG ~ T4IL ~ T4IU)	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

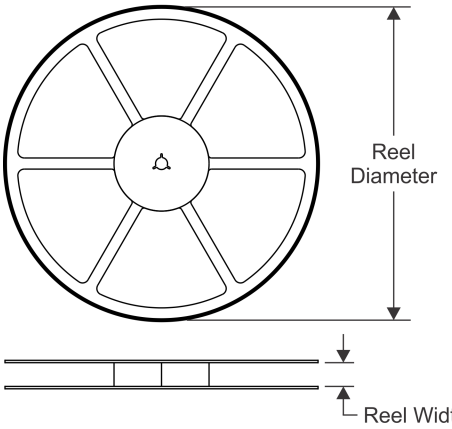
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

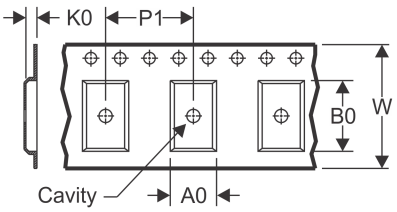
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

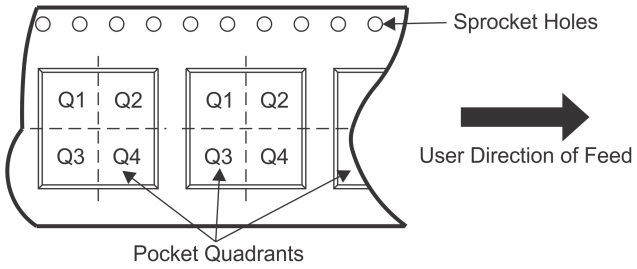


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

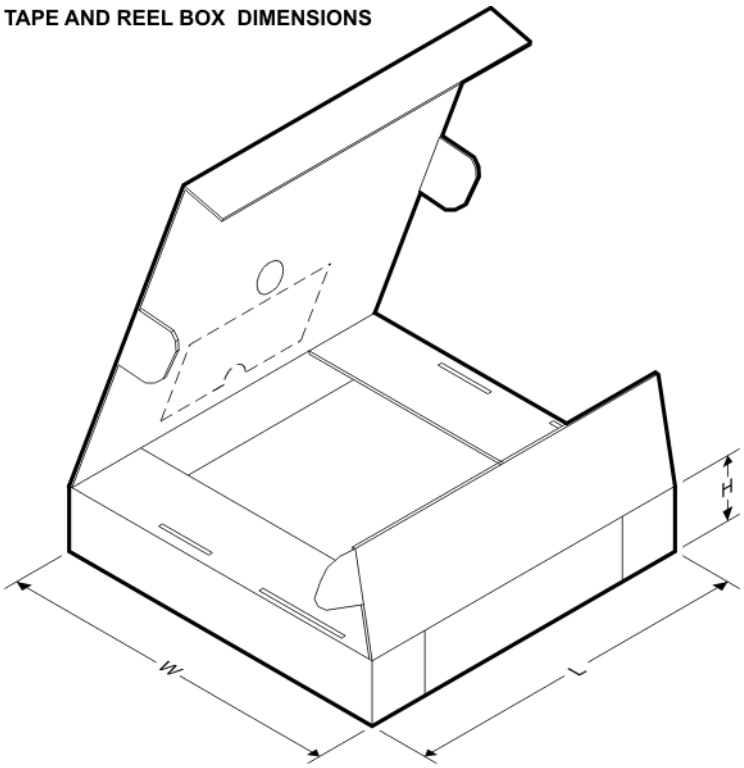
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL343IDBVR	SOT-23	DBV	5	3000	180.0	9.2	3.17	3.23	1.37	4.0	8.0	Q3
TL343IDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TL343IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TL343IDBVT	SOT-23	DBV	5	250	180.0	9.2	3.17	3.23	1.37	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL343IDBVR	SOT-23	DBV	5	3000	205.0	200.0	33.0
TL343IDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TL343IDBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TL343IDBVT	SOT-23	DBV	5	250	205.0	200.0	33.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265